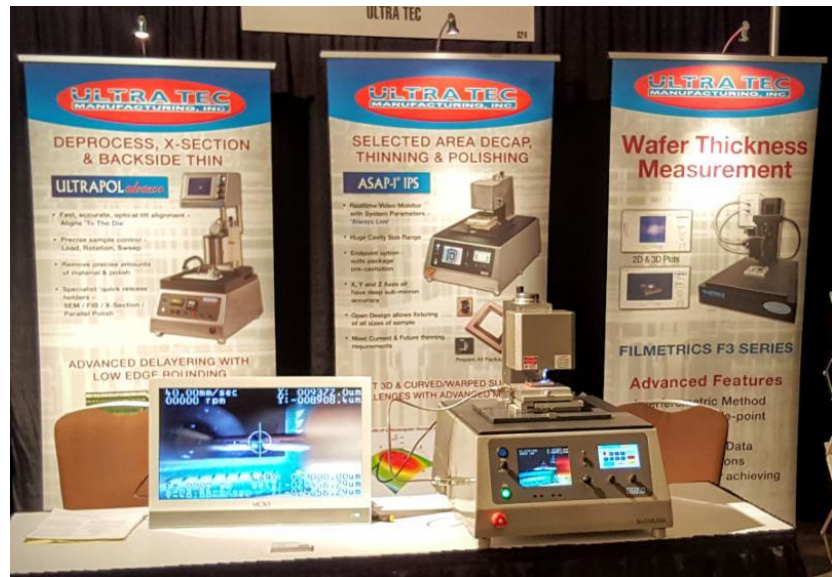




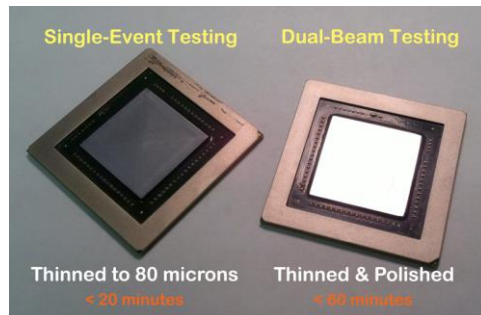
Spring / Summer 2016

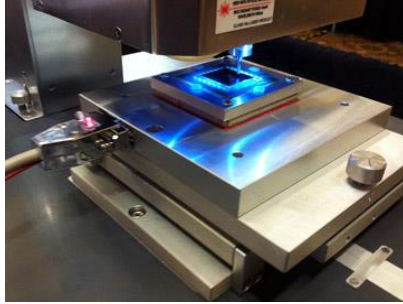
ULTRA TEC DEVICE BACKSIDE THINNING & POLISHING EQUIPMENT

A Complete line of sample preparation tools



Thank you for your interest in ULTRA TEC's products! As many of you have seen at **recent industry symposia**, BACKSIDE THINNING & POLISHING is now available in an accurate, affordable, high-yield, bench-top form... called the **ASAP-1® IPS Selected Area Preparation System**.





Recent advances and improvements allow for **thinner and more accurate Remaining Silicon Thickness (RST) to be achieved with very high yields.** Ask us for more details!

We look forward to working with you!!

ASAP-1® IPS

Digital Selected Area Preparation System

ASAP-1® IPS offers deep sub-micron control on X, Y and Z axes,. ASAP-1® IPS enhances the market-leading attributes of our legacy backside preparation products with the latest digital technology.



Digital Control - Done Right!



Touchscreen control of all parameters ASAP-1® IPS

Mechanical Decapsulation & Topside Delayering both benefit from the system's deep sub-micron accuracy. Our patented 'float down' polishing head design is retained -- offering the means for producing the quality of final polish demanded by customers for **backside microscopy.**

Device Set-up is Fast & Easy

-- Click on the Video Below to See



Video: ASAP-1 IPS Quick Set-up Guide

BACKSIDE PREPARATION PROCESS



Step 1 Decapsulation



Step 2 Heat Sink Milling



Step 3 Substrate Thinning



Steps 4 5 Pre-polish



Step 6 Final Polish

2 Step Decapsulation Process (-5-10 minutes)

- Only required for encapsulated dice

1 Step Substrate Thinning Process (-5-10 minutes)

Produces GRAYED Surface ready for RAD TESTING

Thin down to **160 microns**
80 microns
or thinner

3 Step Polishing Process Process (-30 minutes)

- Only if required

Suits LASER Test methods

FOR MORE INFO ON ASAP-1 www.ultratecusa.com

Through-Silicon Wafer Thickness Measurement



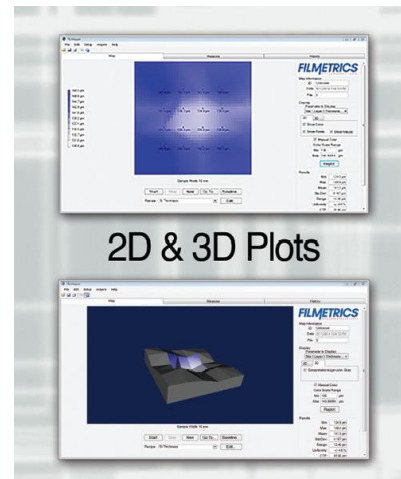
The [F3-XXX Thickness Measurement System](#) offers single or multi-point non contact measurement of silicon, and other semiconductor substrates. It is the perfect accessory for precise thinning and polishing with [ASAP-1 IPS](#).

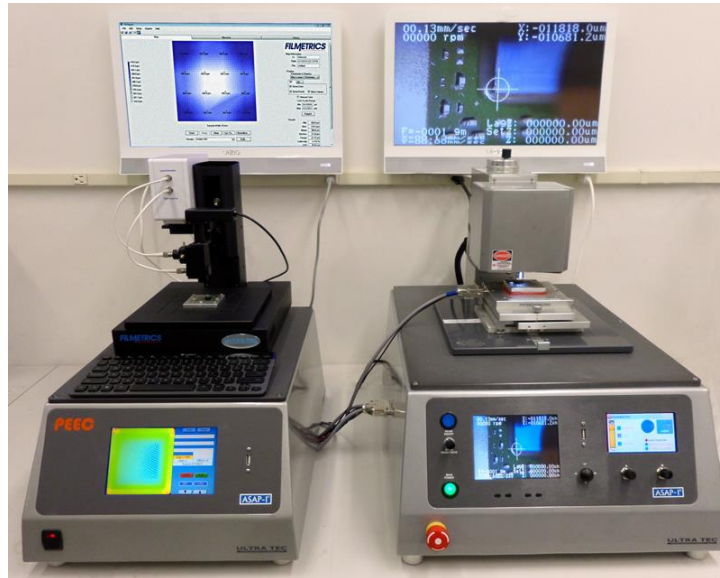
Designed and developed by a team that specializes in a range of thin film and related measurement tools, the [F3-XXX](#) provides accurate measurement of substrate materials

-- from full die thickness to moderately thinned die.

Reproducible results can also be achieved on pre-polished and even gray (lapped) surfaces.

The measured points can be produced as a stepped matrix across the device being prepared, and can be saved in Report or as data-sets -- This allows for process modification and helps ensure the best thickness uniformity results are achieved.





Add F3-XXT to your Integrated sample prep lab

ASAP-1[®] ANALOG SYSTEMS

Effective & Affordable Sample Preparation for Every Lab

ASAP- 1

[®] incorporates controls to achieve the alignment and processing of all sizes packages and samples - from sub-mm die / FIB trenches, right up to large flip-chip CPU modules. The system provides X-Y amplitude control -- providing up to 1 inch (25.4mm) maximum cavity size, or an optional 2 inch (50mm) amplitude upgrade, for large large dice and cavities.



The X-Y Independent table movement is now fitted as standard, allowing for single axis trenching and improved angular alignment. ASAP-1's tilt table is maintained, allowing for 'in package' tilt to be accommodated, along with the ability to translate the ULTRACOLLIMATOR signal into fast accurate sample

alignment. Recent upgrades to the tool drive include the option for a 3X torque motor, providing the power required to optimize heavy milling and material removal.

ABOUT ULTRA TEC

Strength in Design, Manufacture and Global Support

ULTRA TEC Manufacturing, Inc. is a thriving Southern California-based small business. Our continued success is due to having great products, and in having the ability to **manufacture, support and sell** those products to the high tech industries of the world.

Our applications laboratory allows for the development of new tools and processes and offers a crucial customer interface through extensive in-house application development, sample preparation and product training. Our products are used by many domestic and international service labs.

We offer a wide range of surface and sample preparation equipment along with their attendant accessories. To find out more about the value we can add to your organization, please visit www.ultratecusa.com or contact us direct.



Our equipment is widely used throughout the World's product analysis, process development, QC and QA labs.

Please feel free to contact us any time if you have further questions, or need immediate technical or cost information.

We thank you for your interest and we look forward to working with you !

The ULTRA TEC Applications Team



Sample Prep.....done right!

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HRB/trade register number 13424,
Geschäftsführer/General Manager Reinhold Hess
| Nicolas Schwarz

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